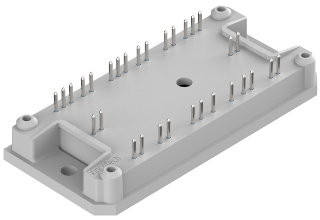
10-FY126PA050M7-L828F08
datasheet

*flow*PACK 1 | 1200 V / 50 A

Features

- IGBT Mitsubishi gen 7 technology with low VCEsat and improved EMC behavior
- Compact and low inductive design
- Built-in NTC

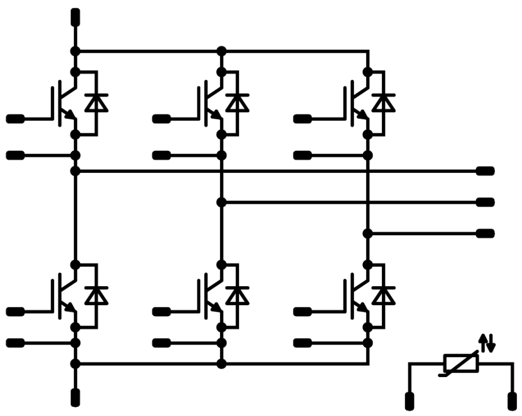
flow 1 12 mm housing



Target applications

- Power Supply
- Solar Inverters
- UPS
- Welding & Cutting

Schematic



Types

- 10-FY126PA050M7-L828F08

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Inverter Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$	T_s = 80 °C	57	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		100	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	115	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 800 V	T_j = 150 °C	9,5	µs
Maximum junction temperature	T_{jmax}			175	°C
Inverter Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	45	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		100	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	78	W
Maximum junction temperature	T_{jmax}			175	°C
Module Properties					
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{jop}			-40…+(T_{jmax} - 25)	°C
Isolation Properties					
Isolation voltage	V_{isol}	DC Test Voltage*	t_p = 2 s	6000	V
Isolation voltage	V_{isol}	AC Voltage	t_p = 1 min	2500	V
Creepage distance				min. 12,7	mm
Clearance				7,81	mm
Comparative Tracking Index	CTI			> 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$			10	0,005	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		50	25 125 150		1,55 1,77 1,83	1,9 (1)	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			0,09	mA
Gate-emitter leakage current	I_{GES}		20	0		25			0,5	µA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}		0	10		25		10000		pF
Output capacitance	C_{oes}							350		pF
Reverse transfer capacitance	C_{res}							130		pF
Gate charge	Q_g	V_{CC} = 600 V	15		50	25		380		nC
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						0,82		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 8 Ω R_{goff} = 8 Ω	±15	600	50	25 125 150		176 176 190		ns
Rise time	t_r					25 125 150		52 58 60		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		206 229 241		ns
Fall time	t_f					25 125 150		92,14 124,72 122,14		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=4,93 µC Q_{rFWD}=7,08 µC Q_{rFWD}=8,04 µC				25 125 150		4,82 6,38 6,25		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		2,98 4,25 5,03		mWs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				50	25 125 150		1,66 1,78 1,79	2,1(1)	V
Reverse leakage current	I_R	V_r = 1200 V				25			40	µA
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,22		K/W
Dynamic										
Peak recovery current	I_{RRM}	d*i*/d*t*=338 A/µs d*i*/d*t*=450 A/µs d*i*/d*t*=498 A/µs	±15	600	50	25 125 150		28,72 32,83 32,97		A
Reverse recovery time	t_{rr}					25 125 150		339,05 434,87 511,31		ns
Recovered charge	Q_r					25 125 150		4,93 7,08 8,04		µC
Reverse recovered energy	E_{rec}					25 125 150		1,79 2,59 3,33		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		194,94 128,35 114,47		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Thermistor										
Static										
Rated resistance	R					25		4,7		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 401 Ω				100	-5		5	%
Power dissipation	P							5		mW
Power dissipation constant	d					25		1,3		mW/K
B-value	$B_{(25/50)}$	Tol. ±3 %						3612		K
B-value	$B_{(25/100)}$	Tol. ±3 %						3650		K

(1) Value at chip level

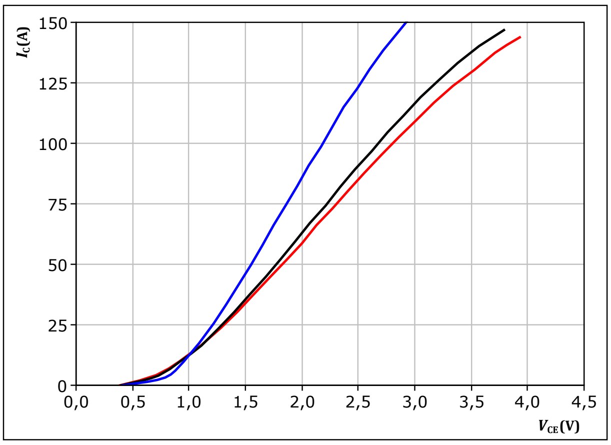
(2) Only valid with pre-applied Vincotech thermal interface material.

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$



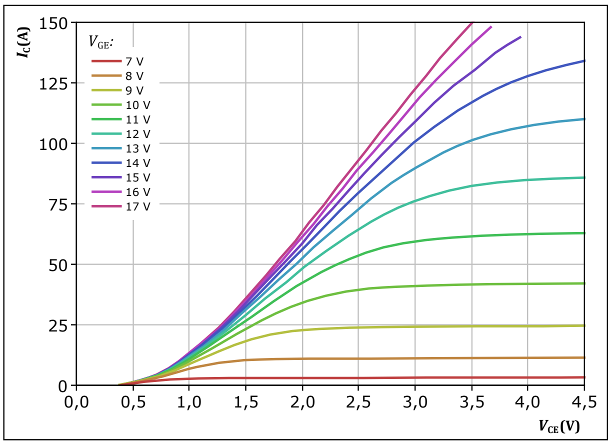
t_p =	250	µs
V_{GE} =	15	V

T_j: 25 °C, 125 °C, 150 °C

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$



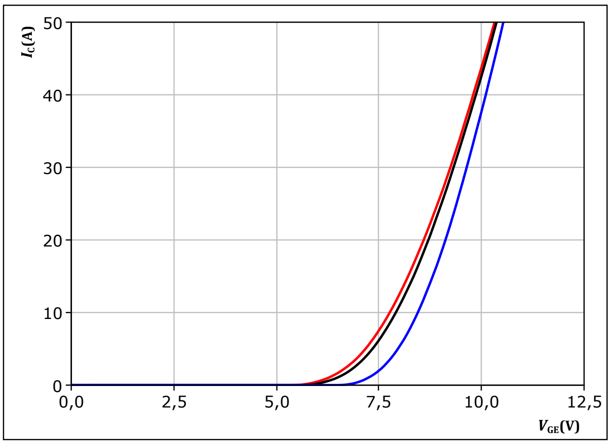
t_p =	250	µs
T_j =	150	°C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$



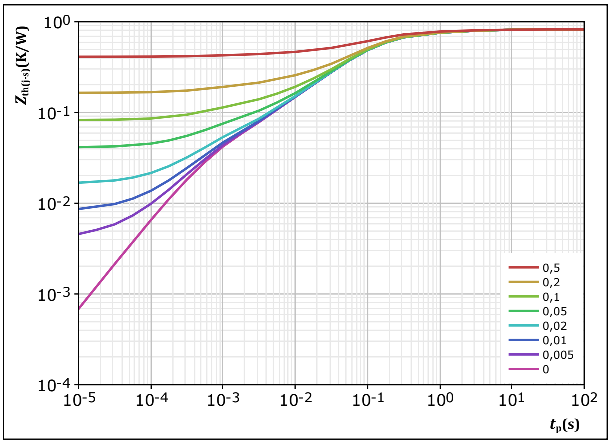
t_p =	250	µs
V_{CE} =	10	V

T_j: 25 °C, 125 °C, 150 °C

figure 4. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 0,823 K/W

IGBT thermal model values

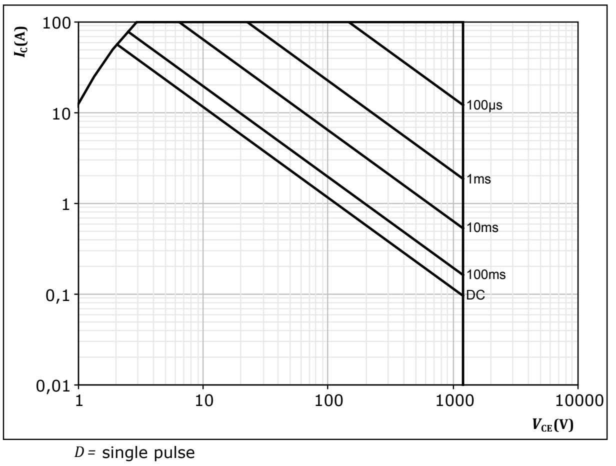
R (K/W)	τ (s)
4,05E-02	5,17E+00
8,54E-02	1,03E+00
3,18E-01	1,67E-01
2,80E-01	5,49E-02
6,47E-02	7,32E-03
3,43E-02	6,46E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

I_C = f(V_{CE})



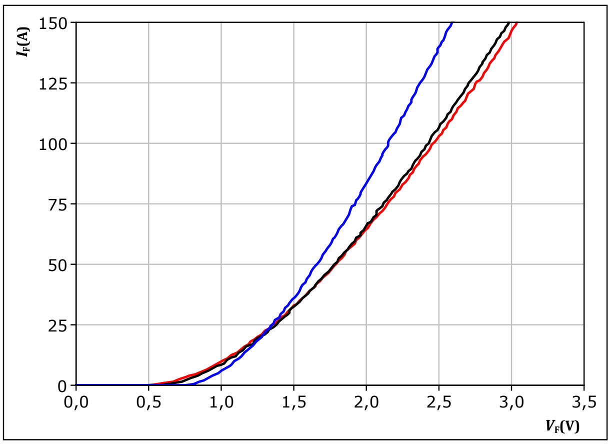
D = single pulse
T_s = 80 °C
V_{GE} = 15 V
T_j = T_{jmax}

Inverter Diode Characteristics

figure 6. **FWD**

Typical forward characteristics

I_F = f(V_F)



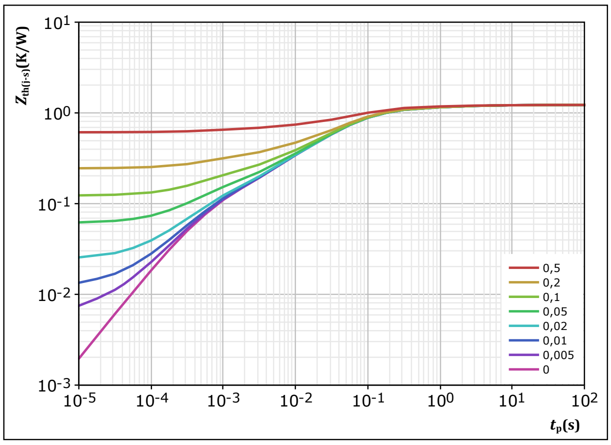
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 7. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T

$R_{th(j-s)}$ = 1,224 K/W

FWD thermal model values

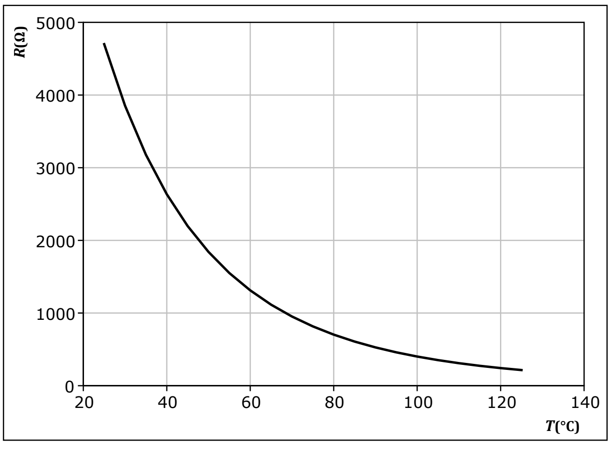
R (K/W)	τ (s)
3,84E-02	6,82E+00
9,89E-02	9,92E-01
3,93E-01	1,28E-01
4,67E-01	3,75E-02
1,41E-01	5,65E-03
8,52E-02	5,44E-04

Thermistor Characteristics

figure 8.	Thermistor

Typical NTC characteristic as function of temperature

R_T = f(T)

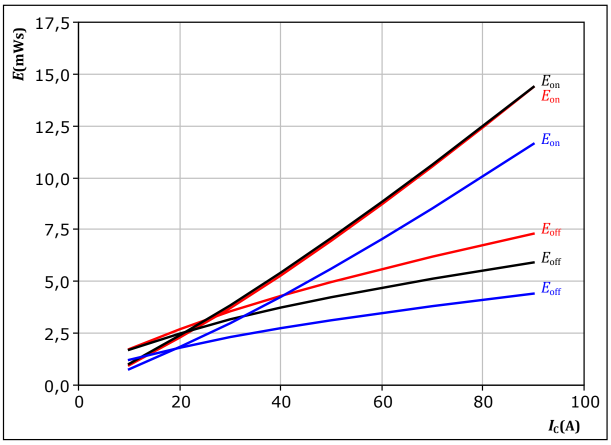


Inverter Switching Characteristics

figure 9. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



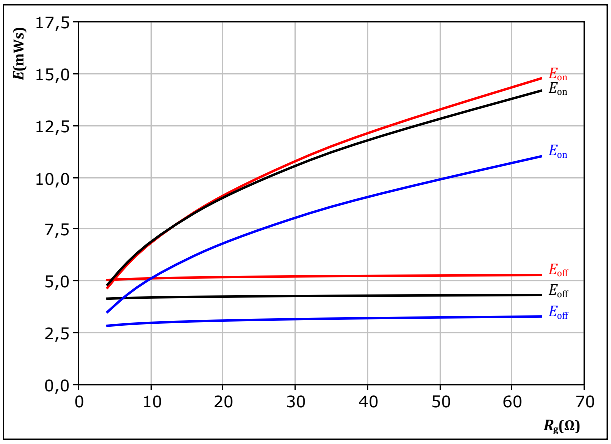
With an inductive load at

V_{CE} =	600	V	T_j: 25 °C
V_{GE} =	±15	V	125 °C
R_{gon} =	8	Ω	150 °C
R_{goff} =	8	Ω	

figure 10. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



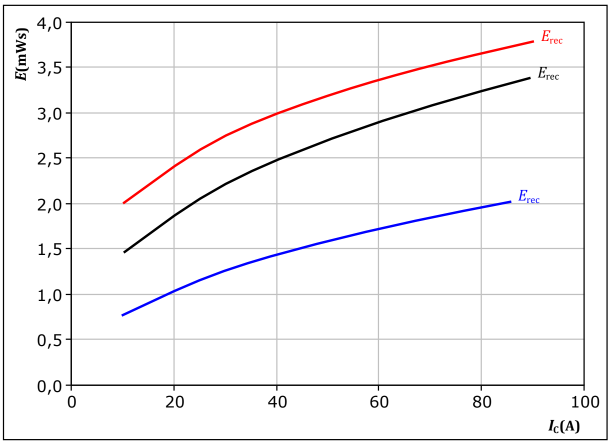
With an inductive load at

V_{CE} =	600	V	T_j: 25 °C
V_{GE} =	±15	V	125 °C
I_C =	50	A	150 °C

figure 11. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



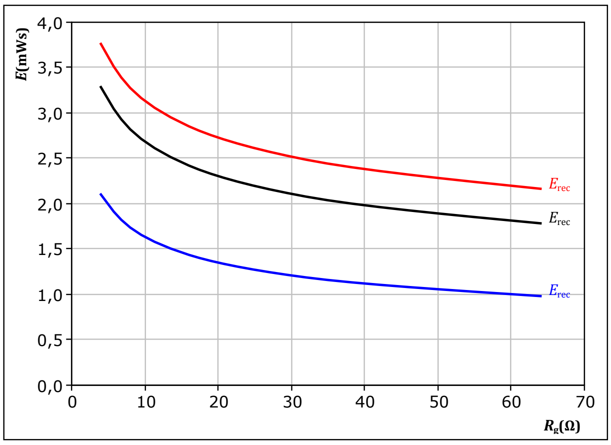
With an inductive load at

V_{CE} =	600	V	T_j: 25 °C
V_{GE} =	±15	V	125 °C
R_{gon} =	8	Ω	150 °C

figure 12. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

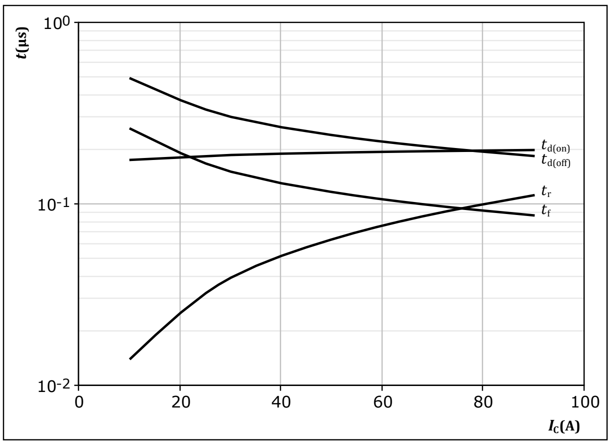
V_{CE} =	600	V	T_j: 25 °C
V_{GE} =	±15	V	125 °C
I_C =	50	A	150 °C

Inverter Switching Characteristics

figure 13. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



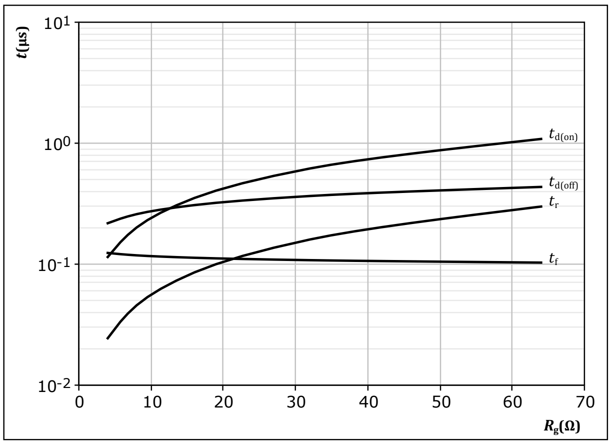
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	8	Ω
R_{goff} =	8	Ω

figure 14. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



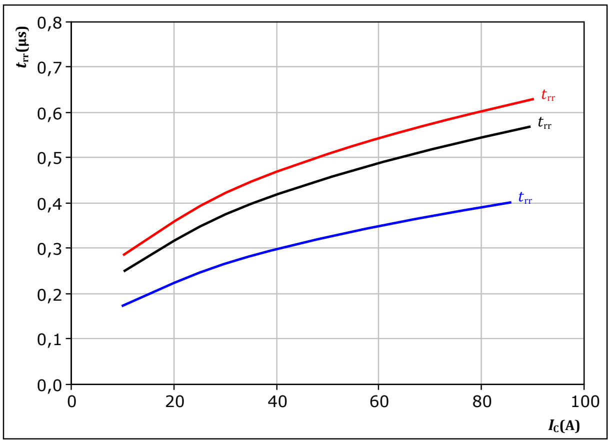
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	50	A

figure 15. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



With an inductive load at

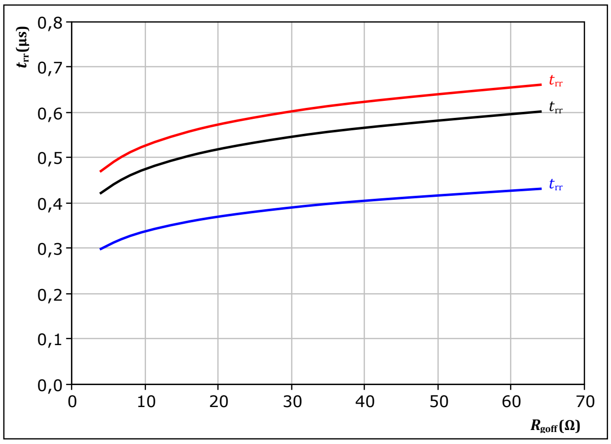
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	8	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 16. **FWD**

Typical reverse recovery time as a function of IGBT turn off gate resistor

$t_{rr} = f(R_{goff})$



With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	50	A

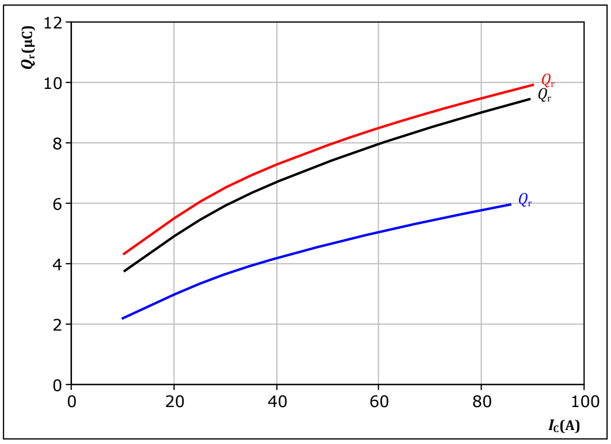
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 17. FWD

Typical recovered charge as a function of collector current

Q_r = f(I_C)



With an inductive load at

V_{CE} = 600 V

V_{GE} = ±15 V

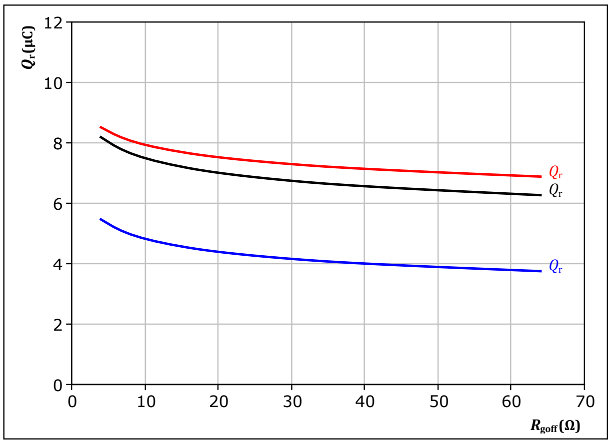
R_{gon} = 8 Ω

T_j: 25 °C, 125 °C, 150 °C

figure 18. FWD

Typical recovered charge as a function of turn off gate resistor

Q_r = f(R_{goff})



With an inductive load at

V_{CE} = 600 V

V_{GE} = ±15 V

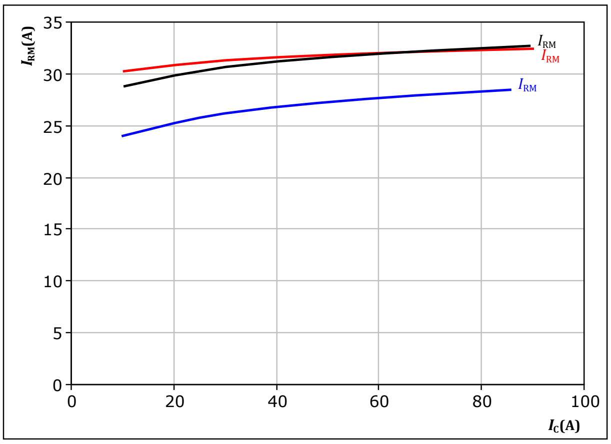
I_C = 50 A

T_j: 25 °C, 125 °C, 150 °C

figure 19. FWD

Typical peak reverse recovery current as a function of collector current

I_{RM} = f(I_C)



With an inductive load at

V_{CE} = 600 V

V_{GE} = ±15 V

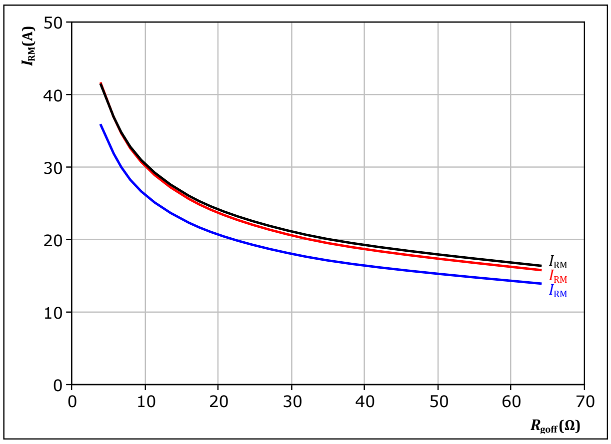
R_{gon} = 8 Ω

T_j: 25 °C, 125 °C, 150 °C

figure 20. FWD

Typical peak reverse recovery current as a function of turn off gate resistor

I_{RM} = f(R_{goff})



With an inductive load at

V_{CE} = 600 V

V_{GE} = ±15 V

I_C = 50 A

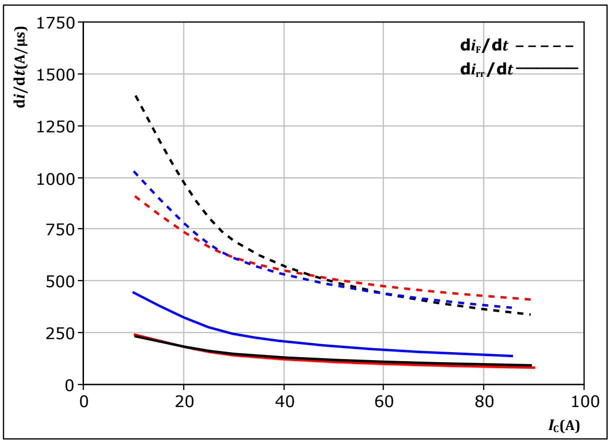
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 21. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



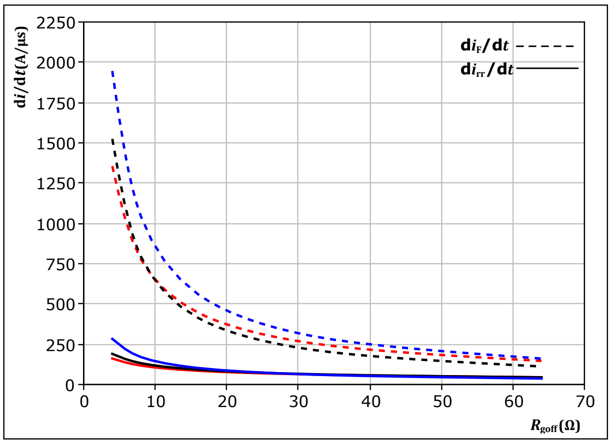
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	8	Ω		150 °C

figure 22. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn off gate resistor

di_F/dt, di_{rr}/dt = f(R_{goff})



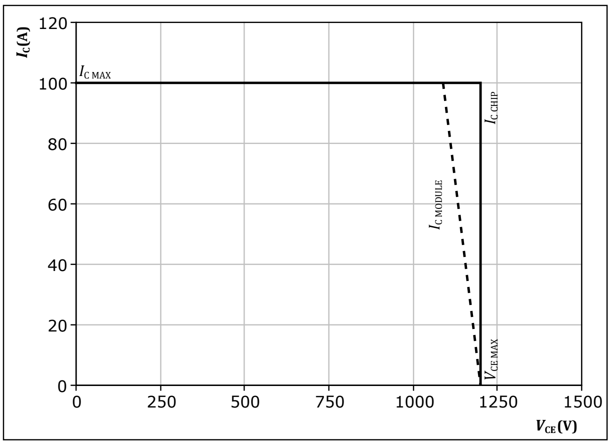
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	50	A		150 °C

figure 23. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



At	T_j =	150	°C
	R_{gon} =	8	Ω
	R_{goff} =	8	Ω

Inverter Switching Definitions

figure 24. **IGBT**

Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{tEoff} = integrating time for E_{off})

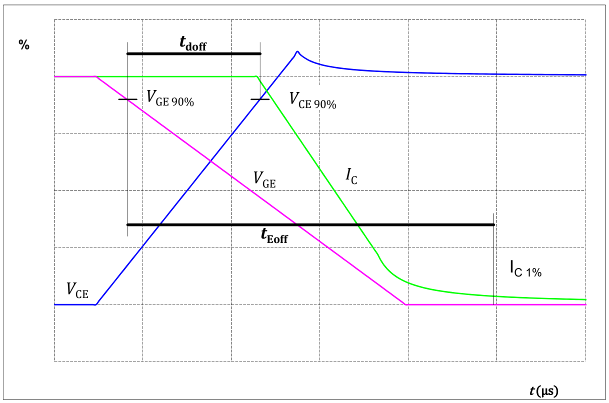


figure 25. **IGBT**

Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})

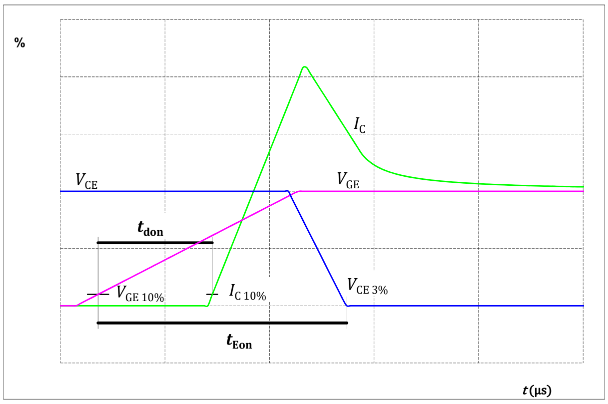


figure 26. **IGBT**

Turn-off Switching Waveforms & definition of t_f

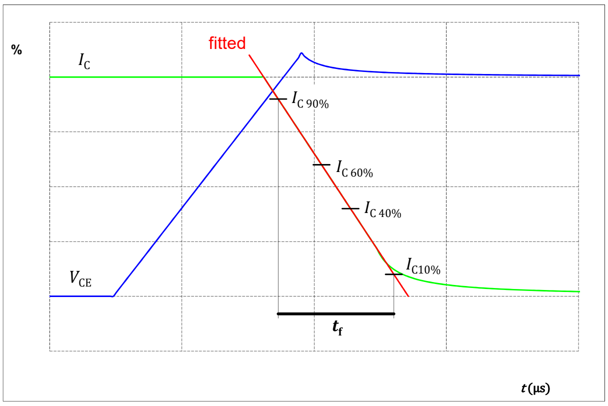
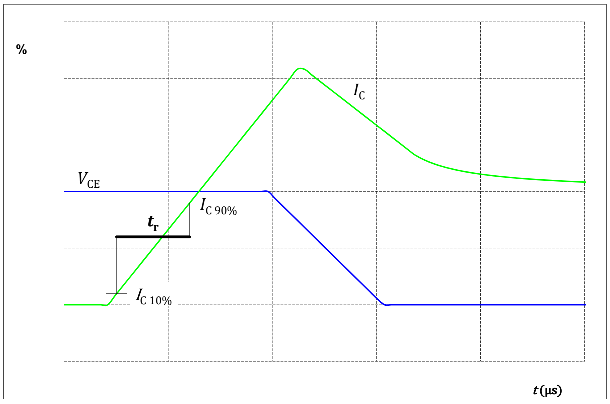


figure 27. **IGBT**

Turn-on Switching Waveforms & definition of t_r



Inverter Switching Definitions

figure 28. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

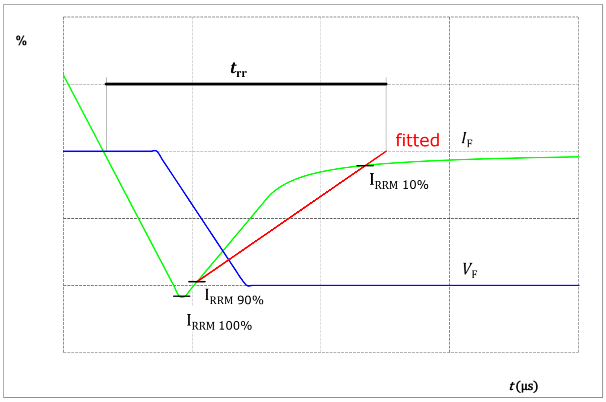
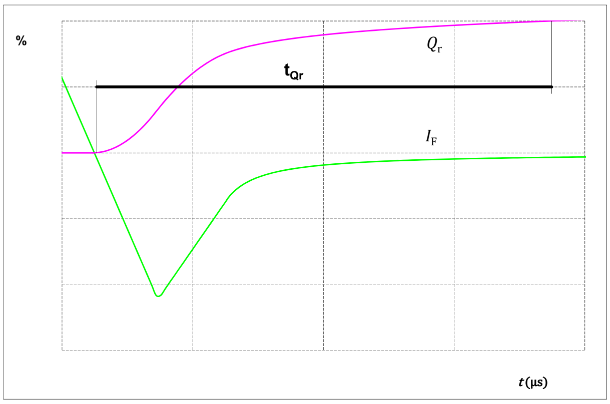


figure 29. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} **(** t_{Qr} **= integrating time for** Q_r**)**



Ordering Code

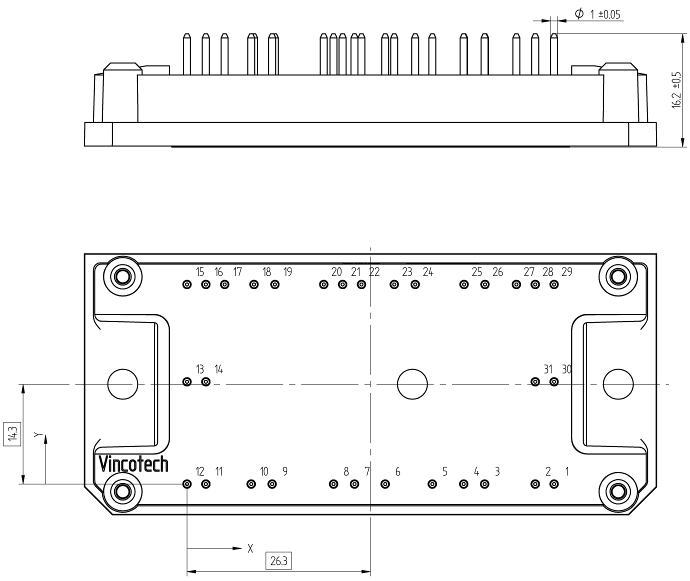
Version	Ordering Code
Without thermal paste	10-FY126PA050M7-L828F08
With thermal paste (5,2 W/mK, PTM6000HV)	10-FY126PA050M7-L828F08-/7/
With thermal paste (3,4 W/mK, PSX-P7)	10-FY126PA050M7-L828F08-/3/

Marking

	Name		Date code	UL & VIN	Lot	Serial
Text	NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
	Type&Ver	**Lot number**	**Serial**	**Date code**		
Datamatrix	TTTTTTTVV	LLLLL	SSSS	WWYY		

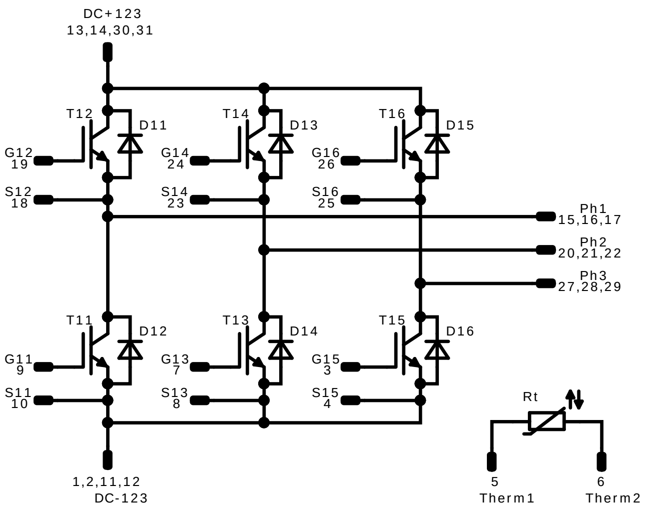
Outline

Pin table [mm]			
Pin	X	Y	Function
1	52,6	0	DC-123
2	49,9	0	DC-123
3	42,65	0	G15
4	39,65	0	S15
5	35,15	0	Therm1
6	28,4	0	Therm2
7	24	0	G13
8	21	0	S13
9	12,2	0	G11
10	9,2	0	S11
11	2,7	0	DC-123
12	0	0	DC-123
13	0	14,65	DC+123
14	2,7	14,65	DC+123
15	0	28,6	Ph1
16	2,7	28,6	Ph1
17	5,4	28,6	Ph1
18	9,6	28,6	S12
19	12,6	28,6	G12
20	19,6	28,6	Ph2
21	22,3	28,6	Ph2
22	25	28,6	Ph2
23	29,7	28,6	S14
24	32,7	28,6	G14
25	39,7	28,6	S16
26	42,7	28,6	G16
27	47,2	28,6	Ph3
28	49,9	28,6	Ph3
29	52,6	28,6	Ph3
30	52,6	14,65	DC+123
31	49,9	14,65	DC+123



Tolerance of pinpositions: ±0,5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	1200 V	50 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	1200 V	50 A	Inverter Diode	
Rt	Thermistor			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* 1 packages see vincotech.com website.

Package data
Package data for *flow* 1 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-FY126PA050M7-L828F08-D3-14	1 Sep. 2021	New Datasheet format, module is unchanged Correct Rth of Inverter Diode	